

# MATERIAL DECLARATION SHEET



Material	MF-NSML Series
Product Line	Multifuse
Revision Date	Oct. 2, 2017
Revision	D
RoHS Compliant	Yes
Halogen Free Compliant	Yes

No.	Breakdown of part (eg Lead, Ceramic body, coating, plating, additive)	Material/substance name (eg.Sn alloy, Cu Copper)	Material/ substance weight in grams (±0.1%)	CAS No. / Int. Identifier	Material /substance weight %	Sum(%)		
1	Metal Carbide	Titanium Carbide	0.0065833	12070-08-5	44.132%	44.132%	44.1319%	
2	Copper Plating	Copper	0.0010606	7440-50-8	7.109%	7.109%	7.1096%	
3	Foil	Copper	0.0029675	7440-50-8	19.893%	20.940%	19.8932%	
		Nickel	0.0001562	7440-02-0	1.047%			1.0470%
4	PCB Foil	Copper	0.0017619	7440-50-8	11.811%	11.811%	11.8109%	
5	Polymer	Polyethylene Homopolymer	0.0005165	9002-88-4	3.462%	3.467%	3.4624%	
		Proprietary Additives	0.0000008	-	0.005%			0.0050%
6	Prepreg	Epoxy	0.0011975	35948-25-5	8.028%	12.282%	8.0278%	
		Glass fiber	0.0006346	65997-17-3	4.254%			4.2540%
7	Solder Plating	Nickel	0.0000380	7440-02-0	0.255%	0.259%	0.2547%	
		Gold	0.0000005	7440-57-5	0.004%			0.0034%
		Total Weight (%)						
			Total weight (grams)	0.0149172	Total	100.000%	100.00%	100.00%